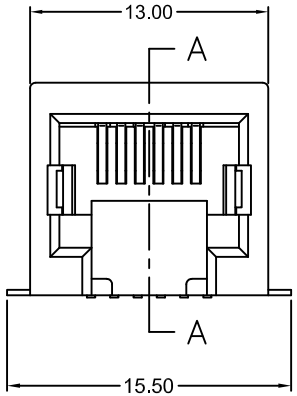
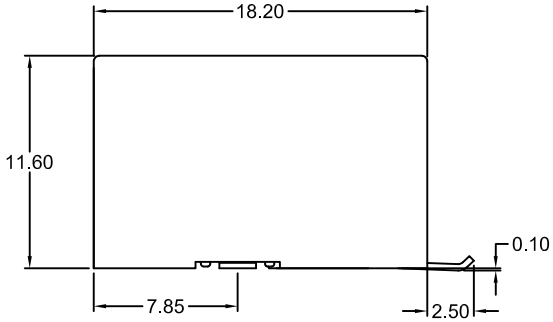
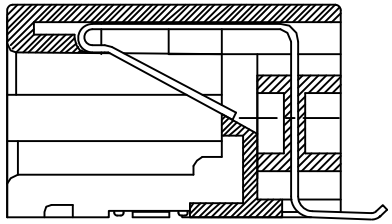
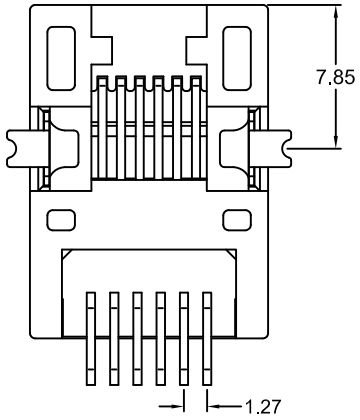
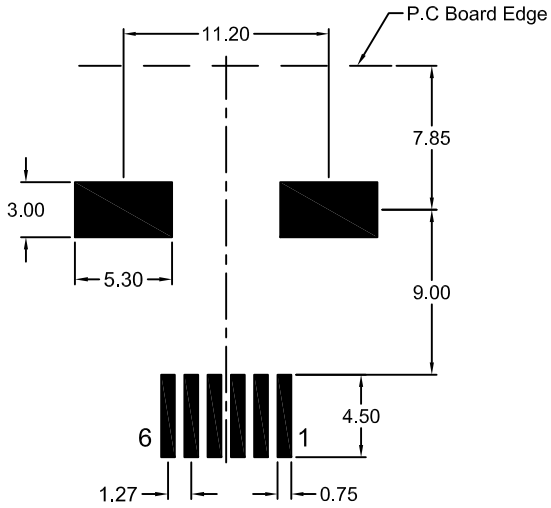
REV.	DESCRIPTION	DRAWN	DATE
A	Release	Ronny	16.02.2011
B	New DWG. No	Ronny	01.02.2012











Recommended PCB SMT Layout
(PCB TOLERANCE ±0.05)

RoHS 2002/95/EC compliant

SPECIFICATIONS

1. MATERIAL
   - HOUSING: LCP UL94V-0 (black)
   - CONTACT: PHOSPHOR BRONZE t=0.35mm
   - PLATING: Au CONTACT AREA; Sn SOLDER AREA
     ENTIRE CONTACT Ni UNDERPLATED

2. ENVIROMENTAL
   - STORAGE TEMPERATURE: -40°C TO +85°C
   - OPERATING TEMPERATURE: 0°C TO +70°C
   - PROCESSING TEMPERATURE:
     +230°C FOR 40 Sec. max.
     +245°C FOR 5 Sec. max.
   - OPERATING LIFE: 750 CYCLES min.

3. ELECTRICAL
   - CURRENT RATING: 1,5A max. (@25°C)
   - VOLTAGE RATING: 125V AC RMS
   - CONTACT RESISTANCE: 50 m OHM max.
   - DIELECTRIC WITHSTANDING VOLTAGE:
     1000V AC rms 1 MINUTE (60Hz)
   - INSULATION RESISTANCE:
     500 M OHM min.

4. CAVITY CONFIRMS TO FCC RULES AND REGISTRATION PAR68, SUBPARTS F.

5. PACKING: TRAY STANDARD; REEL OPTION

Blank : Tray packing
/R = Reel packing

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-W0M0-96 /R	6µ"
MJS-166-W0M0-97 /R	15µ"
MJS-166-W0M0-98 /R	30µ"
MJS-166-W0M0-9H /R	50µ"

E-tec Interconnect

UNIT	mm
SCALE	Free

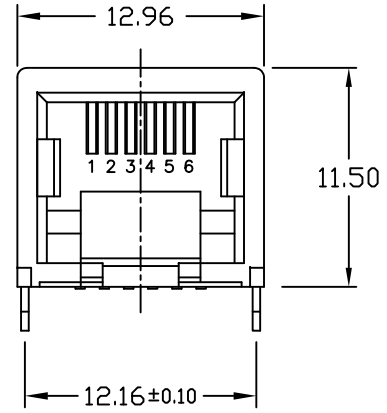
GENERAL TOLERANCE	
X.° ± 3°	.X ° ±
X. ±	.X0 ± 0.38
XX. ±	.XX ± 0.25
XXX. ±	.XXX ±

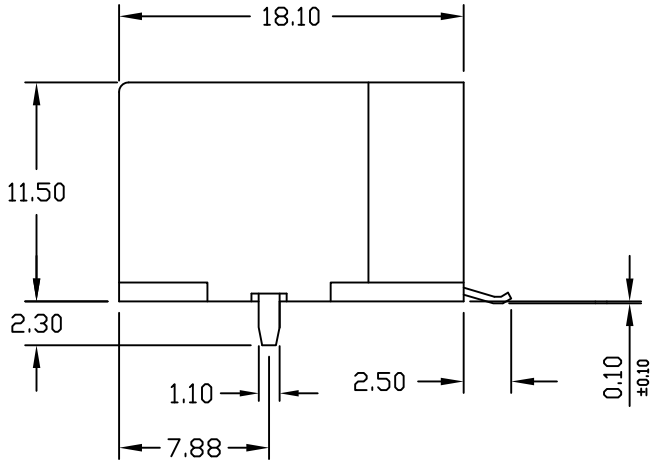
DRAWN	Ronny	DATE 16.02.2011
CHECK	Ronny	DATE 01.02.2012
APPROVE	Hogi	DATE 01.02.2012

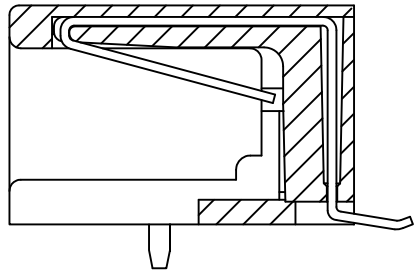
DWG. NO. 1711300 — SHEET 1/1
Series NO. MJS-166-W0M0-9x/X — REV. B

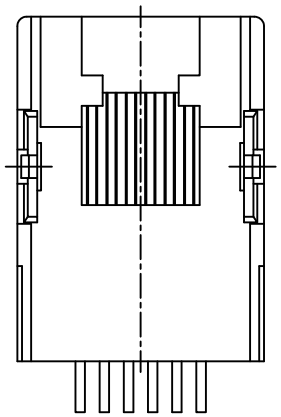
SMT PCB JACK SIDE ENTRY
RJ12 <6P6C> non shielded
wing solder tabs

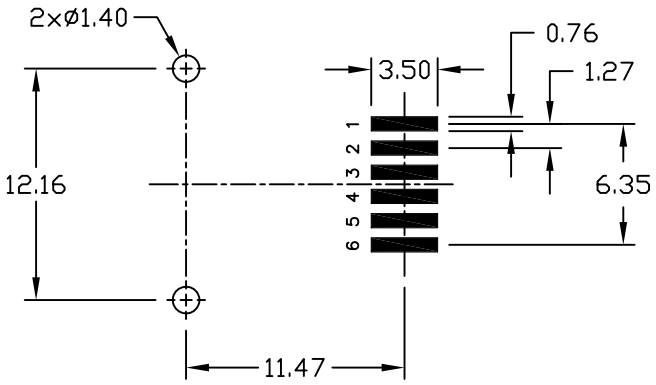
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
A		NEW	09.02.2008	KATHY
B		update description	03.02.2011	Ronny
C		New DWG. No.	01.02.2012	Ronny











PCB LAYOUT TOP VIEW

RoHS 2002/95/EC compliant

NOTE

1. Material:

Housing: Nylon UL 94V-0

Contact: Phosphor Bronze

Contact plating: Sn over Ni on solder area
Au over Ni on contact area

2. Electrical:

Currant rating: 1.5A max. @ 25°C

Voltage rating: 150V AC max.

Contact resistance: 15m Ohm max.

Dielectric withstanding Voltage:
1000V rms 1 Minute 60Hz

Insulation resistance: 500M Ohm min.

3. Enviromental:

Operating temperature: -20°C to +85°C

Processing temperature: 250°C +0/-5°C
for 10 seconds

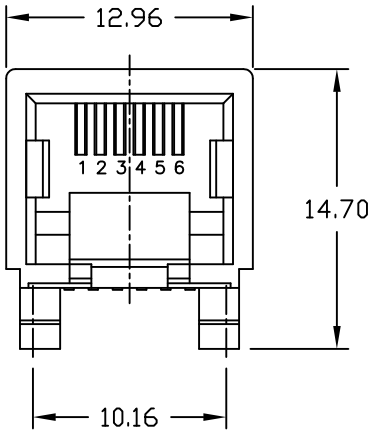
PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-T1S0-96/P	6μ"
MJS-166-T1S0-97/P	15μ"
MJS-166-T1S0-98/P	30μ"
MJS-166-T1S0-9H/P	50μ"

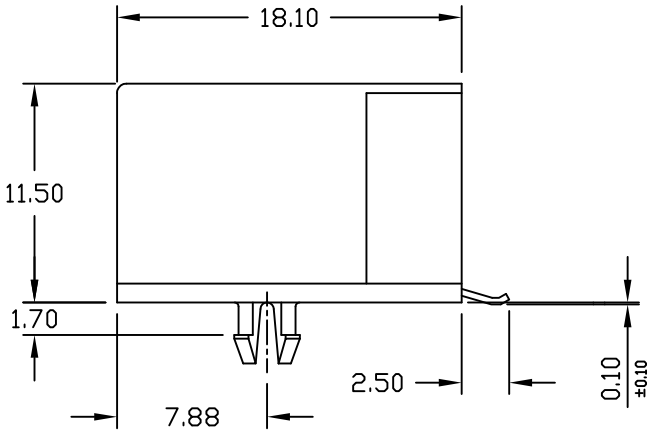
E-tec Interconnect

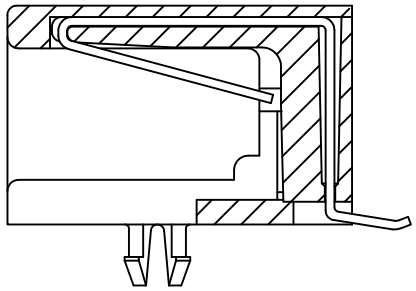
UNIT mm	GENERAL TOLERANCE		DRAWN KATHY	DATE 09.02.2008	DWG. NO. 1711301
SCALE Free	X.° ± 5°	X. ± 0.30	CHECK Ronny	DATE 01.02.2012	SHEET 1/1
	.X° ± 3°	.X ± 0.25	APPROVE HOGI	DATE 01.02.2012	REV. C
	.XX° ± 2°	.XX ± 0.15	SERIES NO. MJS-1xx-T1S0-9x		
	.XXX° ± 1°	.XXX ± 0.10			

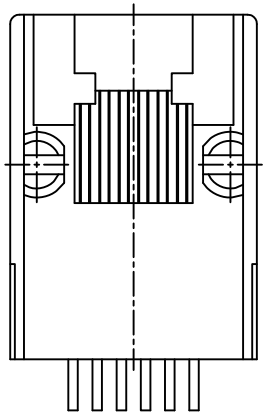
SMT PCB JACK SIDE ENTRY
RJ12 <6P6C> unshielded with straight solder tabs

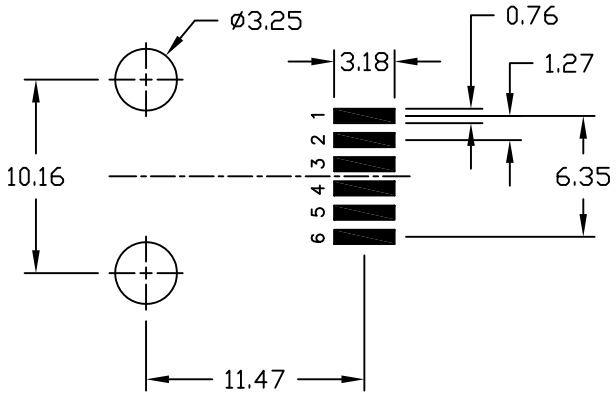
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
A		NEW	17.02.1994	KATHY
B		update description	24.01.2011	Ronny
C		New DWG. No.	01.02.2012	Ronny











PCB LAYOUT TOP VIEW

RoHS 2002/95/EC compliant

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-T1S0-96	6μ"
MJS-166-T1S0-97	15μ"
MJS-166-T1S0-98	30μ"
MJS-166-T1S0-9H	50μ"

NOTE

1. Material:

Housing: Nylon UL 94V-0

Contact: Phosphor Bronze

Contact plating: Sn over Ni on solder area
Au over Ni on contact area

2. Electrical:

Currant rating: 1.5A max. @ 25°C

Voltage rating: 150V AC max.

Contact resistance: 15m Ohm max.

Dielectric withstanding Voltage:
1000V rms 1 Minute 60Hz

Insulation resistance: 500M Ohm min.

3. Enviromental:

Operating temperature: -20°C to +85°C

Processing temperature: 250°C +0/-5°C
for 10 seconds

E-tec Interconnect

UNIT	mm
SCALE	Free

GENERAL TOLERANCE	
X.° ± 5°	X. ± 0.30
.X° ± 3°	.X ± 0.25
.XX° ± 2°	.XX ± 0.15
.XXX° ± 1°	.XXX ± 0.10

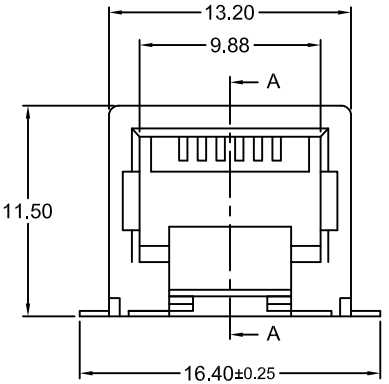
DRAWN	Kathy	DATE 17.02.1994
CHECK	Ronny	DATE 01.02.2012
APPROVE	Hogi	DATE 01.02.2012

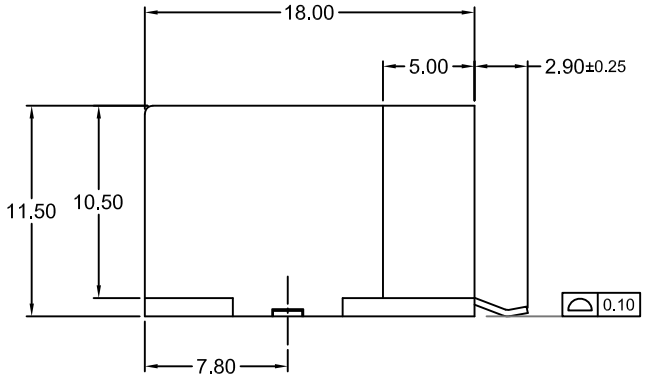
DWG. NO. 1711302 SHEET 1/1 REV. C

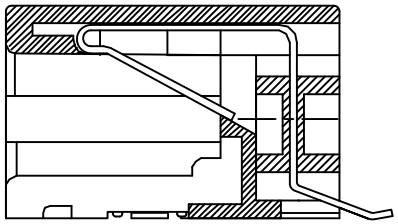
SERIES NO. MJS-1xx-T1S0-9x

SMT PCB JACK SIDE ENTRY
RJ12 <6P6C>
UNSHIELDED

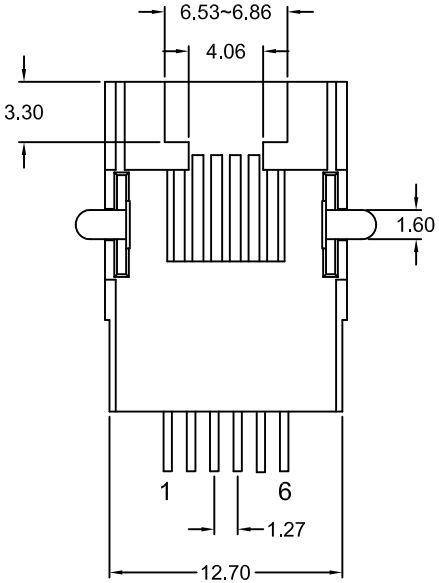
REV.	DESCRIPTION	DATE	DRAWN
A	NEW	22.02.2010	Ryan Chou
B	P/N -W3S1- -> -WD3S1-	28.06.2013	Ronny

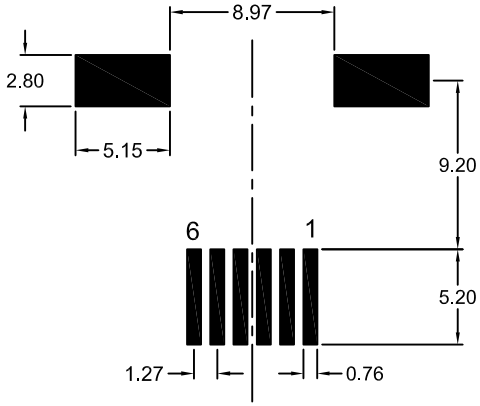






A-A





Recommended PCB SMT Layout
(PCB TOLERANCE ±0.05)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-WD3S1-56/R	6μ"
MJS-166-WD3S1-57/R	15μ"
MJS-166-WD3S1-58/R	30μ"
MJS-166-WD3S1-5H/R	50μ"

RoHS 2002/95/EC compliant

Specifications

Current rating: 1.5A
Insulation resistance: 500MΩ min. / 500V DC
Withstanding voltage: 1000V rms 60Hz / Minute
Contact resistance: 40mΩ max. / 20mV DC

Materials

Contact: Phosphor Bronze t=35mm
Plating: Au flash in solder area
Insulator: PA9T UL 94V-0 (Black)

Operating temperature: -40°C to +105°C
Processing temperature: +250°C +0/-5°C
for 10 seconds

Cavity confirms to FCC Rules and
Registration PAR68, Subparts F.

E-tec Interconnect

UNIT	mm
SCALE	Free

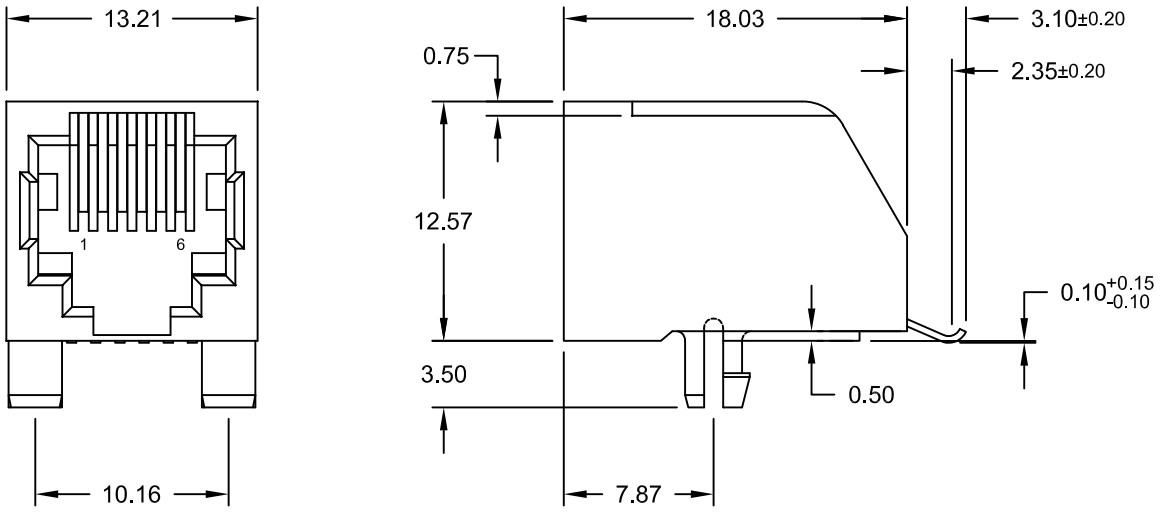
GENERAL TOLERANCE	
X.° ±	.X ±
X. ±	.X ± 0.25
XX. ±	.XX ± 0.13
Ang. ± 0° 30'	.XXX ± 0.05

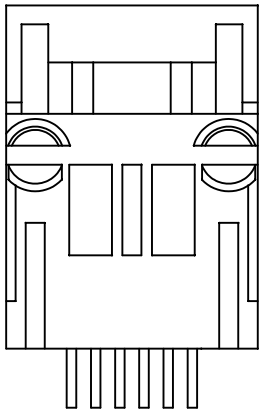
DRAWN	Ryan Chou	22.02.2010
CHECK	Ronny	28.06.2013
APPROVE	Hogi	28.06.2013

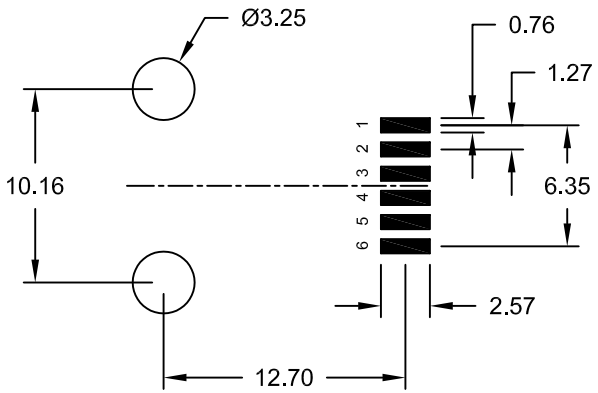
DWG. NO. 1711303
SHEET 1/1
Series NO. MJS-166-WD3S1-5x/X
REV. B

SMT PCB JACK SIDE ENTRY
(RJ11) RJ12 <6P6C> non shielded
wing solder tabs

REV.	DESCRIPTION	DATE	DRAWN
A	NEW	13.10.2014	Ronny







Recommended PCB Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-T1S1-96	6µ"
MJS-166-T1S1-97	15µ"
MJS-166-T1S1-98	30µ"
MJS-166-T1S1-9H	50µ"

RoHS compliant

Specifications

Electrical

Current rating: 1A
Insulation resistance: 500MΩ min.
Voltage rating: 150V AC max.
Withstanding voltage: 1000V AC rms (60Hz / Minute)
Contact resistance: 40mΩ max.

Material

Contact: Phosphor Bronze t=0.35mm
Plating: Sn on solder area;
Au on contact area (see PN code)
Insulator: Nylon PA6T UL 94V-0 (Black)

Operating temperature: -40°C to +85°C
Processing temperature: +250°C +0/-5°C
for 10 seconds

Cavity confirms to FCC Rules and
Registration PAR 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

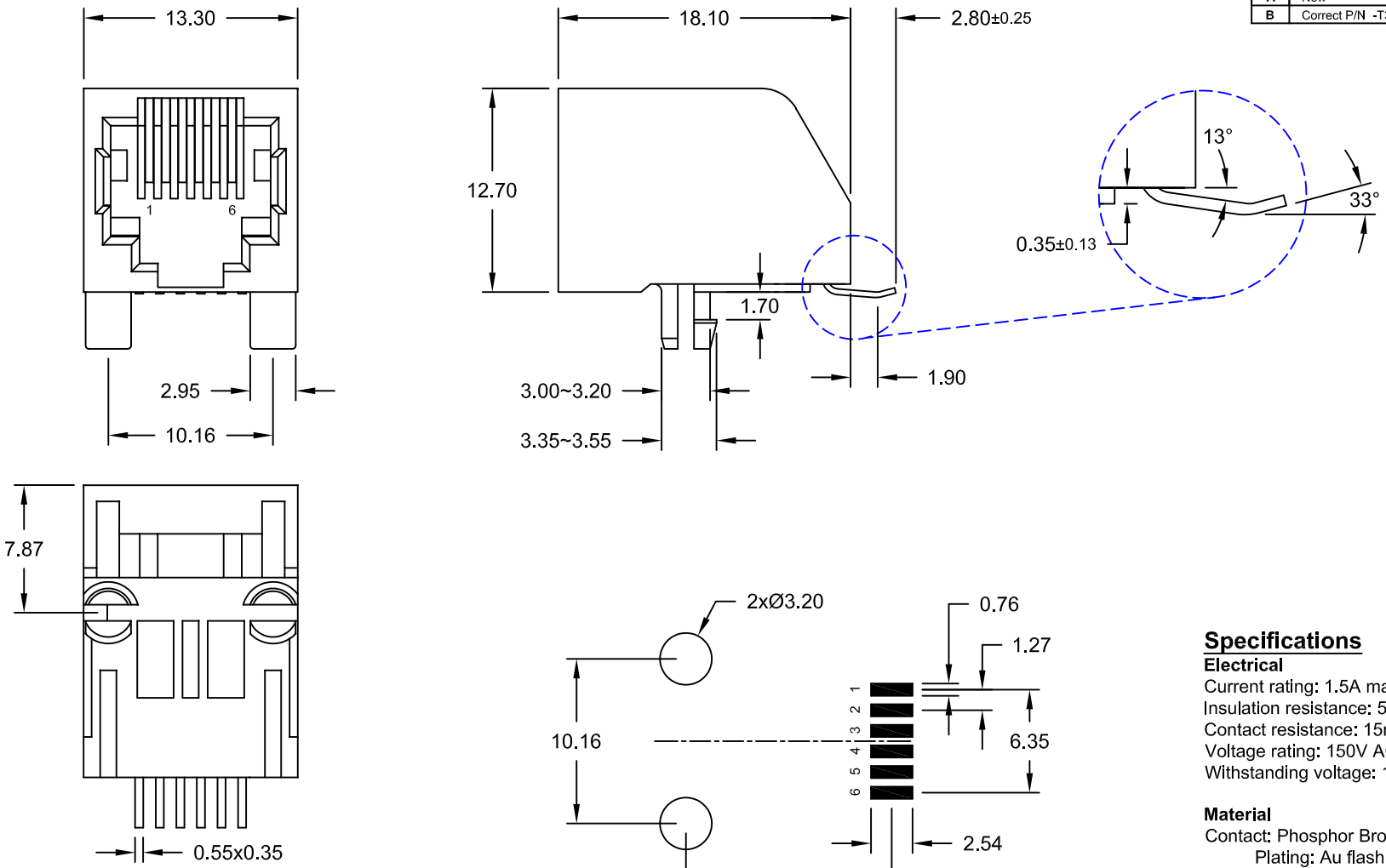
GENERAL TOLERANCE	
X.° ±	X. ± 0.50
.X° ±	.X ± 0.38
.XX° ±	.XX ± 0.25
Ang ± 3°	.XXX ± 0.10

DRAWN	Ronny	DATE 13.10.2014
CHECK	Ronny	DATE 13.10.2014
APPROVE	Hogi	DATE 13.10.2014

DWG. NO. 1711304 SHEET 1/1 REV. A
SERIES NO. MJS-1xx-T1S1-9x

SMT PCB JACK SIDE ENTRY
RJ12 <6P6C>
UNSHIELDED
Material Nylon PA6T

REV.	DESCRIPTION	DATE	DRAWN
A	New	13.10.2014	Ronny
B	Correct P/N -T3S0- -> -TRD3M0-	08.03.2016	Ronny



PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-TRD3M0-56	6µ"
MJS-166-TRD3M0-57	15µ"
MJS-166-TRD3M0-58	30µ"
MJS-166-TRD3M0-5H	50µ"

Recommended PCB Layout Top View
(Tolerance ±0.05)

RoHS compliant

Specifications

Electrical
Current rating: 1.5A max. (@25°C)
Insulation resistance: 500MΩ min.
Contact resistance: 15mΩ max.
Voltage rating: 150V AC max.
Withstanding voltage: 1000V rms / Minute (60Hz)

Material
Contact: Phosphor Bronze
Plating: Au flash on solder area;
Au on contact area (see PN code)
Insulator: PA46 (black) UL 94V-0

Operating temperature: -40°C to +85°C
Processing temperature: +250°C +0/-5°C
for 10 secondss

Cavity comply with FCC Rules and Regulations Part 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ±
.XX° ±	.XX ± 0.25
.XXX° ±	.XXX ±

DRAWN	Ronny	DATE 13.10.2014
CHECK	Hogi	DATE 08.03.2016
APPROVE	Hogi	DATE 08.03.2016

DWG. NO. 1711305 SHEET 1/1 REV. B
SERIES NO. MJS-166-TRD3M0-xx

SMT PCB Jack RJ12 <6P6C>
Side Entry open body "Tab down"
medium profile NON shielded